

## Index

### **a**

acoustic mismatch model (AMM) 126  
 air cooling technology 313  
 amino functionalization 84–87  
 amino-functionalized carbon nanotubes  
 87–88  
 Archimedes method 166  
 Arrhenius equation 23  
 atomic force microscope (AFM)  
 62–64

### **b**

BN/nitrile butadiene rubber (BN/NBR)  
 221  
 Boltzmann's constant 7, 9, 10, 23, 258,  
 260  
 bond line thickness (BLT) 212, 213,  
 241  
 boron nitride (BN)  
 and amino carbon nanotubes 80–84  
 microspheres 88–93  
 particles 100–107  
 sheet 87–88  
 thermal interface materials 102–107  
 boron nitride nanosheets (BNNS) 77, 93,  
 95–97, 100, 275, 304, 305  
 boron nitride nanotube (BNNT) 110,  
 113, 275  
 Bragg equation 131, 133  
 Bruggeman theoretical model 293, 294  
 buckypaper composites 231

### **c**

carbide-forming elements 130, 143, 145,  
 146, 153  
 carbon–carbon composites 27, 36  
 carbon fiber composites 289  
 carbon nanofibers (CNFs) 102, 106–110,  
 112, 216, 231, 232  
 carbon nanotubes (CNTs) 80–84, 87–88,  
 108, 214, 215, 231, 233, 270, 273,  
 289, 290, 310, 323  
 ceramic packaging 30, 31  
 Cheng–Vochen theoretical model 293  
 chip packaging 23, 26, 306  
 3-chloropropyltriethoxysilane (CPTES)  
 228  
 coefficient of thermal expansion (CTE)  
 26–28, 32, 36, 64, 65, 70, 99,  
 126–130, 142, 161, 213, 229, 268,  
 298, 303  
 cold plate 44, 45, 314  
 composite materials  
 application of 288–290  
 dispersion form 323–324  
 electron conduction mechanism 290  
 electronic heat dissipation 295–296  
 history of 287–288  
 modification of 302–310  
 phonon heat conduction mechanism  
 291  
 preparation and application of  
 296–298

- composite materials (*contd.*)
- reasonable filling amount 320–322
  - research on fillers 327–329
  - structure and morphology 322
  - surface morphology of 322–323
  - thermal adaptation materials 295–296
  - thermal conduction mechanism 291–292
  - thermal conductivity model 293–294
  - thermally conductive potting 326, 327
- covalent bonding 31–33, 215, 221–223, 275, 277–279, 283, 304, 305
- crystallinity 32, 34, 56, 130, 133
- Cu–Cu<sub>x</sub>–O nanoparticles 227
- d**
- de Broglie wavelength 59
- Debye temperature 9, 14
- definite conditions 5
- density factor 22, 213
- diamond/copper composites 146–149, 151, 159–162, 268–270, 303
- diamond/Cu(AI) composites 311–312
- diamond/Cu-B composites 150–152
- dielectric constant 21, 26, 27, 30–32, 49, 52–53, 71, 92, 93, 290, 304
- diffraction pattern processing and analysis system 57
- diffusion mismatch model 126
- direct liquid cooling 314
- dissipation factor 52, 53
- dissipative particle dynamics (DPD) 259–261
- droplet impingement cooling 315
- dynamic thermal mechanical analysis (DMA) 66, 68
- e**
- e-DPD method 259–261, 263–265
- EBSD 122, 124
- elastic theory 128
- elastomers 66, 235–237, 324–326
- electric conductivity and resistivity
- bulk material testing 50
  - four-probe method 50–51
  - Van der Pauw method 51–52
- electromagnetic wave 53
- electron conduction mechanism 290
- electron gas 6, 117
- electronic device
- direct liquid cooling 314
  - indirect liquid cooling 314
  - liquid jet cooling 315
  - and spraying, drop cooling 315
- electronic heat dissipation 295, 296, 319
- electronic packaging
- definition of 19, 20
  - electrical connection 20
  - functions of 20, 21
  - heat dissipation path 21
  - levels of 21, 22
  - standardization of integrated circuit 20–21
- electrostatic flocking method 308
- energy dissipation mechanisms 237
- epoxy molding compound (EMC) 26, 27
- epoxy potting glue 324, 325
- f**
- fiber-reinforced polymer (FRP) 288
- filler surface functionalization 214, 215
- flip chip ball grid array (FC-BGA) 117, 118
- fluorinated CNT/nanofibrillated cellulose (FCNT/NFC) composite 221, 222
- four-probe method 50, 51
- Fourier's law 2, 3, 211, 257, 258, 261
- g**
- gallium alloys 228
- gallium-based liquid metals 226, 227
- Gr/Cu
- coefficient of thermal expansion 126–130
  - in situ composite method 121–124
  - thermal conductivity of 124–126
- graphene hybrid paper (GHP) 234, 235
- graphene oxide, reduction 84–87
- graphite/Cu composites

compounding process 131–133  
 orientation modulation of 133–136  
 thermal conductivity of 136–140  
 graphite flakes (Gf) 130–136, 141, 143  
 graphite/Gr/Cu composites  
   thermal conductivity of 140–141  
   thermal expansion coefficient of  
     141–143  
 graphite nanosheets (GNP) 126, 303  
 graphite welding 236  
 Green–Kubo method 257, 258  
 guarded heat flow meter method 44, 45  
 guarded hot plate method 43–46

## ***h***

heat-adaptive composite material 295  
 heat conduction differential equation  
   3–5  
 heat conduction mechanism  
   of gas 6  
   of liquids 11–12  
   of solids 6–11  
 heat dissipation substrate 25, 26, 165  
 heat dissipation technology 295–297,  
   313–316, 319  
 heat flow model 220  
 heat flux density field 2, 3, 257, 294, 295,  
   303  
 heat-matching composite material 295  
 heat-resistant composite materials  
   299–300  
 hexagonal boron nitride 77, 78, 80,  
   84–85, 88, 105, 113, 215  
 highly oriented pyrolytic graphite  
   (HOPG) 130  
 high melting point phase (HMP) 224,  
   226, 228  
 high thermal conductive composites  
   configured diamond/metal 157–159  
   configurations 161, 162  
   secondary diamond addition 159–160  
   secondary particle size 160–161  
 high thermal conductive interface  
   boron-modified diamond/Cu  
     composites 150–152  
   chromium-modified diamond/Cu  
     composites 146–149  
   Gr-modified diamond/Cu composites  
     153–157  
   theoretical calculation of 143–145  
 high thermal conductivity 14, 24–28, 30,  
   32, 33, 35, 36, 42, 78–80, 97, 114,  
   117–120, 129, 145, 146, 157–159,  
   165–207, 213, 224–226, 228, 229,  
   231–233, 236, 261, 263, 268, 270,  
   287–330  
 H–J model 126  
 hot disk methods 40, 47, 231  
 hot pressing 80, 122, 131–133, 135, 136,  
   138, 141, 154, 156, 215, 216, 218,  
   326, 327  
 hot-wire method 40, 46, 47, 306  
 hydrogen bonding  
   analysis 109–114  
   defined 102, 109  
   preparation and characterization  
     107–109

## ***i***

ice crystal induction method 308  
 indirect liquid cooling 314  
 inorganic energy storage materials 317  
 inorganic nonmetals  
   crystal structure 8, 9, 14  
   liquids 11, 12  
   noncrystals 9–11  
   others 15  
   pressure 13, 14  
   temperature 12–13  
   thermal resistance 14  
 inorganic thermal conductive silicon  
   carbide fillers 77–78  
 in-plane thermally conductive pathways  
   215–216  
 integrated heat spreader (IHS) 211  
 interfacial thermal resistance (ITR) 92,  
   121, 124–126, 129, 141, 143, 144,  
   146, 147, 149, 150, 152, 157, 229,  
   275, 279, 292, 305, 323, 329

intrinsic thermal conductivity 33–35,  
120, 125, 131, 144–146, 149, 157,  
233, 234, 283, 293, 304  
isothermal surface 1, 42  
isotropic thermally conductive pathways  
220, 221

**j**

Joule's law 22

**k**

Kapitsa thermal resistance 293  
Klemens model 8

**l**

Laplace equation 5  
laser flash method (LFA) 46, 47, 166,  
231, 306  
laser spot 63  
law of conservation of energy 3  
light emission microscopy (LEM) 54  
linear voltage differential transformer  
(LVDT) 65  
liquid cooling technology 313  
liquid jet cooling 315  
liquid phase sintering (LPS) 224  
longitudinal heat flow method 42–44

**m**

magnetic field orientation 217  
Maxwell theoretical model 293  
mean phonon velocity 40  
mechanical machining 237  
metal matrix packaging materials 27–30  
metal thermal management materials  
high thermal conductivity 118  
mechanical properties 118  
thermal expansion coefficient 118  
weldability 118  
microchannel heat transfer microchannel  
315, 316  
minimum thermal conductivity model  
10  
molecular dynamics (MD)  
e-DPD method 259–261

Green–Kubo method 257, 258  
NEMD method 258, 259  
polymer-based composites 270  
polymers 261–265  
TC of diamond/copper composites  
268–270  
TC of  $\text{Si}_3\text{N}_4$  ceramic 265–267  
momentum-swapping algorithm 239

**n**

nanometers 227, 329  
Nielsen theoretical model 293  
nitridation degree (ND) 167  
nitridation rate 165, 176  
non-covalent bonding 221, 275, 283, 305  
nonequilibrium MD (NEMD) method  
239, 258, 259  
non-oxide additives 182, 189, 190  
non-steady-state method  
hot-wire method 46  
laser flash method 46  
measurement method 42  
transient planar heat source (TPS) 47,  
48

**o**

optical microscope 54, 55, 57–59  
optimization ( $\text{YEu}_2\text{O}_3/\text{MgO}$ ) 167–173  
organic energy storage materials  
317–320  
out-of-plane thermally conductive  
pathways 216–219

**p**

packaging materials  
ceramic matrix 30–33  
diamond/Cu(Al) composites 311–312  
high-volume fraction SiCp/Al  
composites 310–311  
metal matrix 27–30  
polymer matrix 33–35  
Papapeccu formula 9  
particle size ratio (PSR) 158–160  
PE chains 261–263  
peeling strength

- of Cu-metalized ceramic substrates 205–207
  - of Cu-metalized  $\text{Si}_3\text{N}_4$  substrates 204–205
  - Pell formula 9
  - percolation theory 53, 291, 292
  - phase analysis 56, 166
  - phase-change-materials (PCM) 25, 231, 295–298, 301, 316–320
  - phase change temperature control 316, 317
  - phase change wetting 223
  - phonon density of states (PDOS) 275
  - phonon heat conduction mechanism 15, 291
  - phonon velocity 40, 144, 145, 153, 156
  - photoemission microscopy 54
  - piezoelectric transducer 61
  - plasma-assisted mechanochemistry 215
  - plastic deformation 69, 70, 121, 223
  - polarization Raman spectroscopy 135
  - polymer-based composites
    - heat transfer pathways construction 270–275
    - low thermal resistance interface structure construction 275–283
  - polymer packaging 33, 35, 310
  - polymethylmethacrylate (PMMA) 120
  - polyurethane elastomer 324–326
  - potting materials
    - classification of 324
    - research of 324–326
  - primary packaging 21, 23
  - pulse echo method 61, 62
- r**
- reliability analysis
    - adherence strength 70
    - failure modes and mechanisms 69–71
    - moisture 70–71
    - residual stress 69–70
    - stress void 70
  - reliability certification
    - high-reliability selection 73
    - humidity measurement 72
  - hygroscopic strain 72
  - moisture test 71–72
  - plastic defects 72, 73
  - plastic packaging material, viscosity of 71
  - quality control 73
  - temperature adaptability 72
  - tightness 72
- S**
- scanning acoustic microscopy (SAM) 60, 62
  - scanning electron microscope (SEM) 57, 58, 69, 101, 108, 166, 180
  - secondary diamond volume (SDV) 158
  - secondary packaging 21–23
  - self-heating effect 117
  - $\text{Si}_3\text{N}_4$  sintered with  $\text{YH}_2$ 
    - densification and weight loss 194–196
    - elements distribution 196–197
    - mechanical properties on 201–203
    - microstructure on 197–200
    - phase composition 196, 197
    - pre-sintering of 191–194
    - $\text{REH}_2$  on 203
    - thermal conductivity on 200–201
  - silicon compact, rapid nitridation of 165–181
  - silicone polymer 33, 324–326
  - sintered reaction-bonded silicon nitride (SRBSN) 165
    - with 2YE5M 173–181
  - sintering additive
    - optimization ( $\text{YEu}_2\text{O}_3/\text{MgO}$ ) 167–173
    - SRBSN with 2YE5M 173–181
  - spray cooling 314, 315
  - steady-state method
    - guarded heat flow meter method 44
    - guarded hot plate method 44, 45
    - longitudinal heat flow method 43, 44
    - measurement method 41, 42
  - super scaffolding 224
  - supersolder 225
  - synergistic effect 96, 144, 304, 305, 309

**t**

- TC of diamond/copper composites 268–270
- TC of  $\text{Si}_3\text{N}_4$  ceramic 265–267
- temperature field 1, 2, 4, 5, 46, 271
- temperature gradient 2, 3, 15, 24, 39, 44, 45, 108, 217, 239, 257, 258, 260, 262, 264, 269, 279, 313, 314, 316
- tertiary packaging 22, 23
- thermal adaptation materials 295, 296
- thermal conduction mechanism 290–292, 305, 309
- thermal conduction model 293, 306
- thermal conductivity model 3, 10, 290–294, 302
- thermal conductivity test
  - atomic force microscope (AFM) 62–64
  - development of 39, 40
  - dielectric constant and its characterization 52, 53
  - dynamic mechanical analysis (DMA) 66–68
  - electric conductivity and resistivity 49–52
  - non-steady-state measurement method 42, 46–48
  - optical microscopy 54, 55
  - scanning acoustic microscopy (SAM) 60–62
  - scanning electron microscope (SEM) 57, 58
  - steady-state measurement method 41, 42
  - thermal mechanical analysis (TMA) 64–66
  - transmission electron microscope (TEM) 58–60
  - X-ray diffraction 55–57
- thermal diffusion coefficient 4, 48, 91, 124, 140, 155, 166
- thermal failure rate 23
- thermal functional composites
  - applications 301
  - conductive composites 299
  - forecast 302
  - heat-resistant composite materials 299, 300
  - thermal storage materials 300, 301
- thermal interface materials (TIM) 24, 25
  - carbon-based 229–238
  - conception of 211–214
  - covalent bonding 215
  - filler surface functionalization 214, 215
  - metal-based 223–229
  - molecular simulation study 238–240
  - polymer-based 214–223
  - thermally conductive pathways 215–221
- thermally conductive pathways
  - covalent bonds 221–223
  - in-plane 215–216
  - isotropic 220–221
  - non-covalent bonds 221
  - out-of-plane 216–219
  - welding 223
- thermal management
  - electronic device heat dissipation technology 313–316
  - phase change temperature control 316–320
  - package level 23–24
- thermal mechanical analysis (TMA) 64–66
- thermal power cycle test 225
- thermal sources
  - density factor 22
  - Joule heat 22–23
  - power density 22
- thermal storage materials 300, 301, 318, 319
- thermoelastic coefficient theory 291, 292
- thermogravimetric (TG) 72, 173, 174
- thermos-dilatometry 64
- thermos-mechanometry 64
- thermostat algorithm 239
- time-domain thermal reflection (TDTR) 155
- transient planar heat source (TPS) 47–48

- transmission electron microscope (TEM) 57–60, 69, 95, 101  
tungsten–copper alloy 119
- U**
- unsteady state method 40
- V**
- vacuum-assisted filtration process 215  
vacuum filtration method 308  
Van der Pauw method 51, 52  
van der Waals (VdW) force 34, 275, 304  
velocity-rescaling algorithm 239  
vertical graphene (VG) 237  
vertically aligned CNTs (VACNTs) 229, 230, 233
- W**
- welding technique 223  
Wiedman–Franz law 7
- X**
- X-ray detector 56, 57  
X-ray diffraction  
  crystallinity 56  
  phase analysis 56  
  precise measurement 56, 57  
X-ray photoelectron spectroscopy (XPS) 123  
X-ray source, high stability 56
- Y**
- Young’s modulus 14, 65, 82, 83, 87, 88, 127, 231, 241
- Z**
- zero-level packaging 21  
ZrSi<sub>2</sub>  
  electrical resistivity of 189–190  
  microstructure on 186–188  
  phase composition on 185–186  
  reaction mechanism of 182–185  
  thermal conductivity of 188, 189



















